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ESDALCL6-2SC6

Very low capacitance and low leakage current ESD protection

Datasheet - production data

Features

- 2 data-line protection
- Protects V_{BUS}
- Very low capacitance: 2.5 pF typ.
- Very low leakage current:
 - 10 nA at 3 V
 - 1 nA at 1 V
- RoHS compliant

Complies with the following standards:

- IEC 61000-4-2 level 4 and higher:
 - 30 kV (air discharge)
 - 15 kV (contact discharge)
- MIL STD883G-Method 3015-7
 - 25 kV (human body model)

Applications

- USB 2.0 ports up to 480 Mb/s (high speed)
- Compatible with USB 2.0
- Ethernet port: 10/100 Mb/s
- SIM card protection
- Video line protection
- Portable healthcare equipment

Description

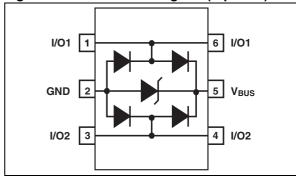
The ESDALCL6-2SC6 is a monolithic application specific device dedicated to ESD protection of high speed interfaces, such as USB 2.0, ethernet links and video lines.

The very low line capacitance secures a high level of signal integrity without compromising in protecting sensitive chips against the most stringently characterized ESD strikes.

Its low leakage current makes it suitable for portable equipment.



Figure 1. Functional diagram (top view)



Characteristics ESDALCL6-2SC6

1 Characteristics

Table 1. Absolute ratings

Symbol	Parameter		Value	Unit
		IEC 61000-4-2 air discharge	30	
V_{PP}	Peak pulse voltage	IEC 61000-4-2 contact discharge	15	kV
		MIL STD883G-Method 3015-7	25	
T _{stg}	Storage temperature range		-55 to +150	°C
T _j	Operating junction temperature range		-40 to +125	°C
TL	Lead solder temperature (10 seconds duration)		260	°C

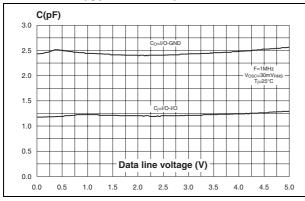
Table 2. Electrical characteristics ($T_{amb} = 25$ °C)

Symbol	Parameter	Test conditions	Value			Unit	
Symbol	Faranietei	rest conditions	Min.	Тур.	Max.	Unit	
V_{BR}	I _R = 1 mA		6			V	
I _{RM}	$V_{RM} = 3 \text{ V}, V_{CC} \text{ to GND}$				10	nA	
	V _{RM} = 1 V, V _{CC} to GND				1		
V _F	Forward voltage	I _F = 10 mA			1.1	V	
V _{CL}	Clamping voltage	I _{PP} = 1 A, 8/20 μs Any I/O pin to GND			12	V	
		I _{PP} = 5 A, 8/20 μs Any I/O pin to GND			17	V	
C _{i/o-GND}	Capacitance between I/O and GND	V 165 V		2.5	3.5	nE	
ΔC _{i/o-GND}	Capacitance between 1/O and GND	VR = 1.05 V		0.015		pF	
C _{i/o-i/o}	Capacitance between I/O	V 1 65 V		1.2	1.7	pF	
$\Delta C_{i/o-i/o}$	Capacitatice Detween I/O	V _R = 1.65 V		0.04			

ESDALCL6-2SC6 Characteristics

Figure 2. Capacitance versus voltage (typical values)

Figure 3. Line capacitance versus frequency (typical values)



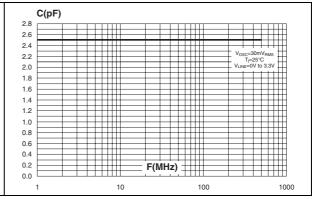
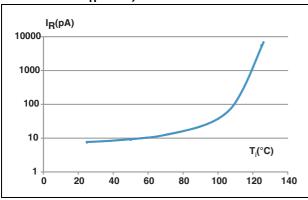


Figure 4. Leakage current versus junction temperature (typical values, $V_B = 1 \text{ V}$)

Figure 5. Leakage current versus reverse applied voltage (typical values)



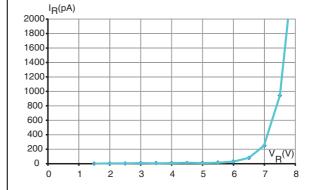
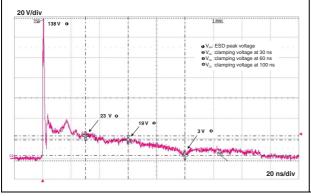


Figure 6. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

Figure 7. ESD response to IEC 6100-4-2 (-8 kV contact discharge)



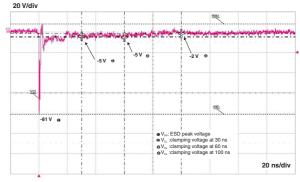
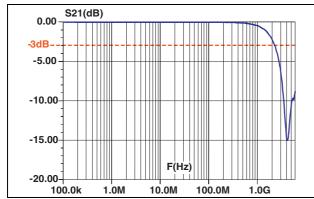
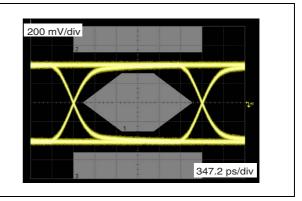


Figure 8. S21 attenuation measurement result

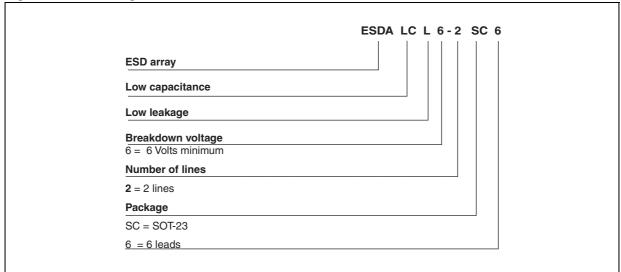
Figure 9. USB2.0 eye diagram





2 Ordering information scheme

Figure 10. Ordering information scheme



3 Package information

- Epoxy meets UL94, V0
- Lead-free packages

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK[®] is an ST trademark.

Table 3. SOT23-6L dimensions

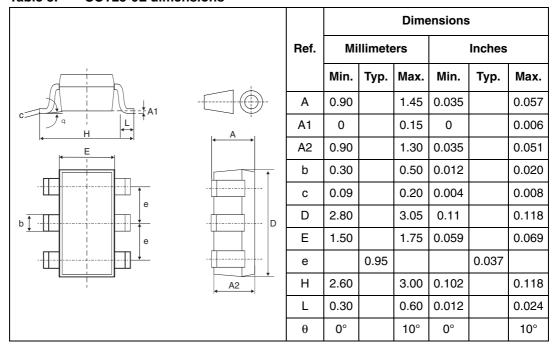
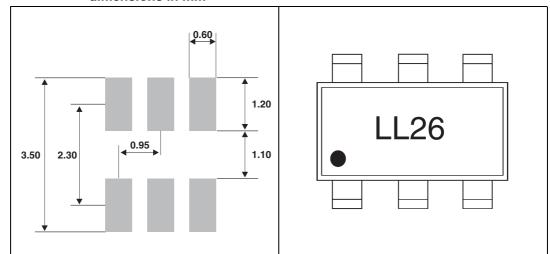


Figure 11. SOT23-6L footprint dimensions in mm

Figure 12. SOT23-6L marking



Ordering information ESDALCL6-2SC6

4 Ordering information

Table 4. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDALCL6-2SC6	LL26	SOT23-6L	16.7 mg	3000	Tape and reel

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
31-Oct-2012	1	First issue.

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